



US00D920397S

(12) **United States Design Patent** (10) **Patent No.:** **US D920,397 S**
Okuma et al. (45) **Date of Patent:** **** May 25, 2021**

(54) **LASER PROCESSING MACHINE**

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(**) Term: **15 Years**

(21) Appl. No.: **29/689,267**

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(30) **Foreign Application Priority Data**

Oct. 31, 2018 (JP) 2018-023968

(51) **LOC (13) Cl.** **15-09**

(52) **U.S. Cl.**
USPC **D15/122**

(58) **Field of Classification Search**

USPC D15/122; D24/108, 164, 169, 170, 233;
D16/230–234; D26/27; D10/81
(Continued)

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(57) **CLAIM**

The ornamental design for a laser processing machine, as shown and described.

DESCRIPTION

FIG. 1 is a front view of a laser processing machine of the present invention;

FIG. 2 is a rear view thereof;

FIG. 3 is a top plan view thereof;

FIG. 4 is a bottom plan view thereof;

FIG. 5 is a right side view thereof;

FIG. 6 is a left side view thereof;

FIG. 7 is a front, top and left side perspective view thereof;
FIG. 8 is a rear, bottom and right side perspective view thereof;

FIG. 9 is an enlarged view thereof defined by the lines 9-9 and 9'-9' in FIG. 1;

FIG. 10 is an enlarged view thereof defined by the lines 10-10 and 10'-10' in FIG. 1 showing the state of movement;

FIG. 11 is an enlarged view thereof defined by the lines 11-11 and 11'-11' in FIG. 6;

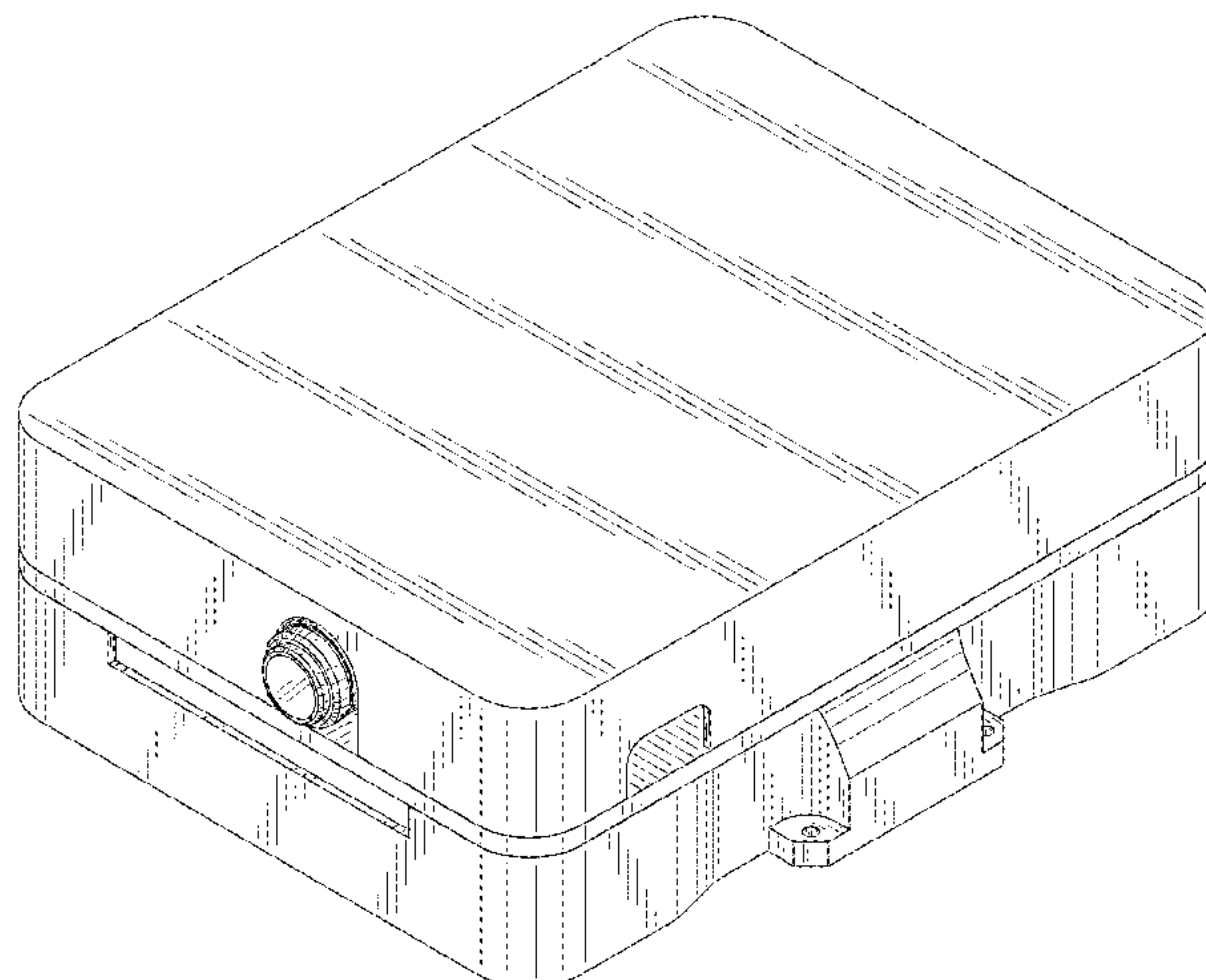
FIG. 12 is a sectional view thereof with inner mechanism is omitted taken along the line 12-12 in FIG. 3; and,

FIG. 13 is an enlarged sectional view thereof with inner mechanism is omitted taken along the line 13-13 in FIG. 5 of the portion defined by the line 13'-13' in FIG. 3.

The broken line showing of the laser processing machine is included for the purpose of illustrating portions of the article and forms no part of the claimed design.

The dash dot dash broken lines define the bounds of the claimed design and form no part thereof.

1 Claim, 13 Drawing Sheets



(58) Field of Classification Search

CPC B23K 26/00; B23K 26/0006;
B23K 26/0096; B23K 26/08; B23K
26/36; B23K 26/32; B23K 26/40; F23G
2204/202; B01D 2259/808; B65C
2009/0043; B65C 2009/1846; B65H
2301/51536; B27K 5/005; B29C
2035/0838; H01L 21/00; H01L 21/67;
H01L 2221/00; H01L 2221/67; H01L
22/10; H01L 23/32; H01L 23/544; H01S
3/00; H01S 3/0007; H01S 3/0014; H01S
3/025; H01S 3/101; H01S 5/00; H01S
5/02; H01S 5/04; H01S 5/10; H05K
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See application file for complete search history.

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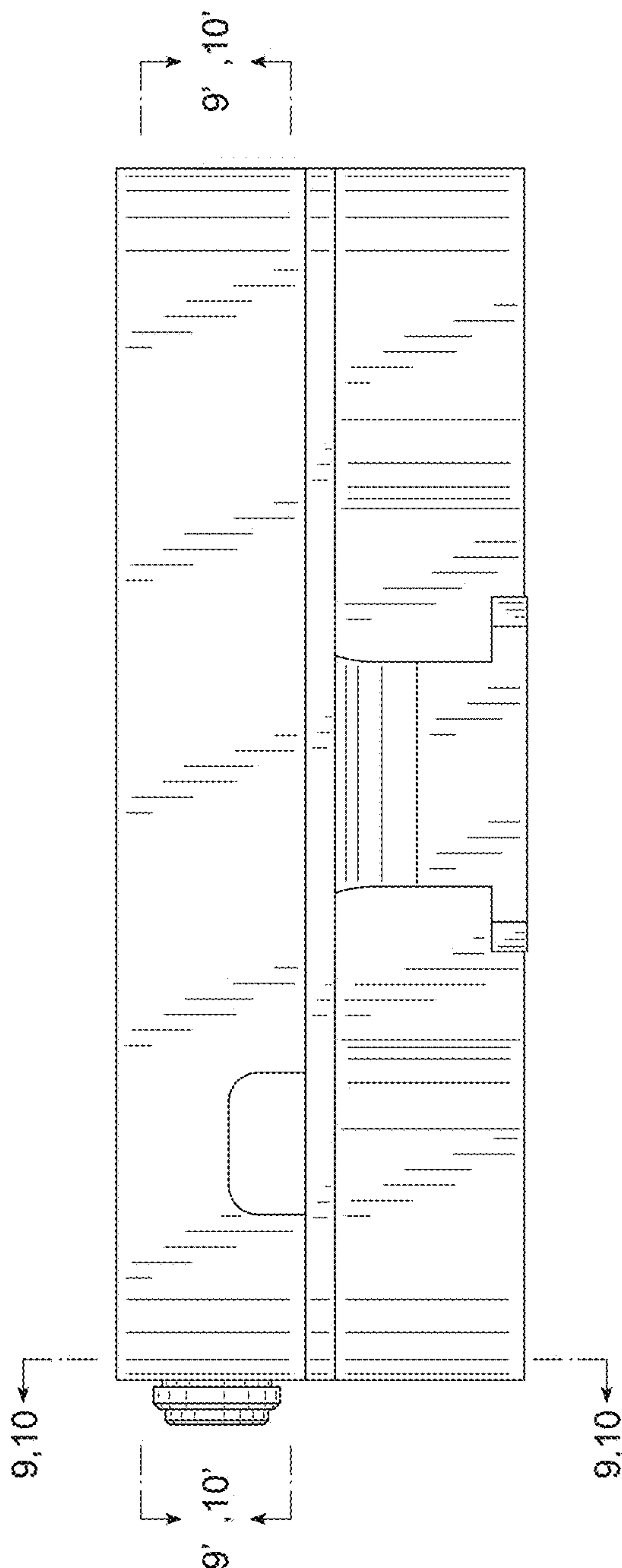


FIG. 1

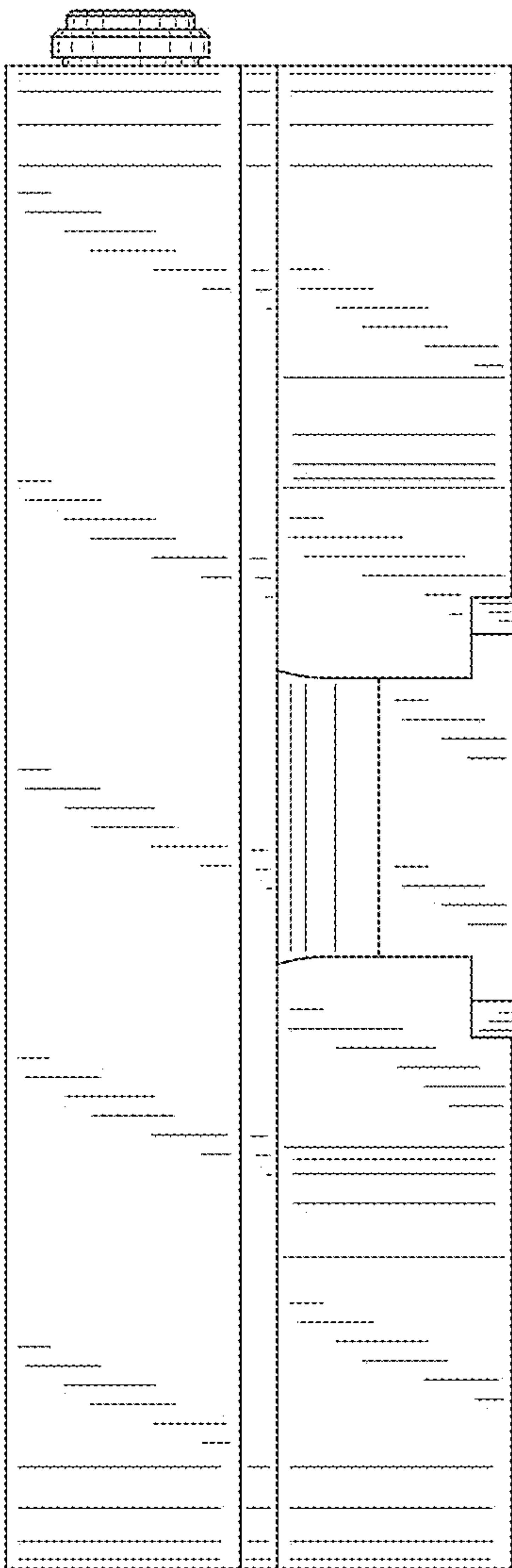


FIG. 2

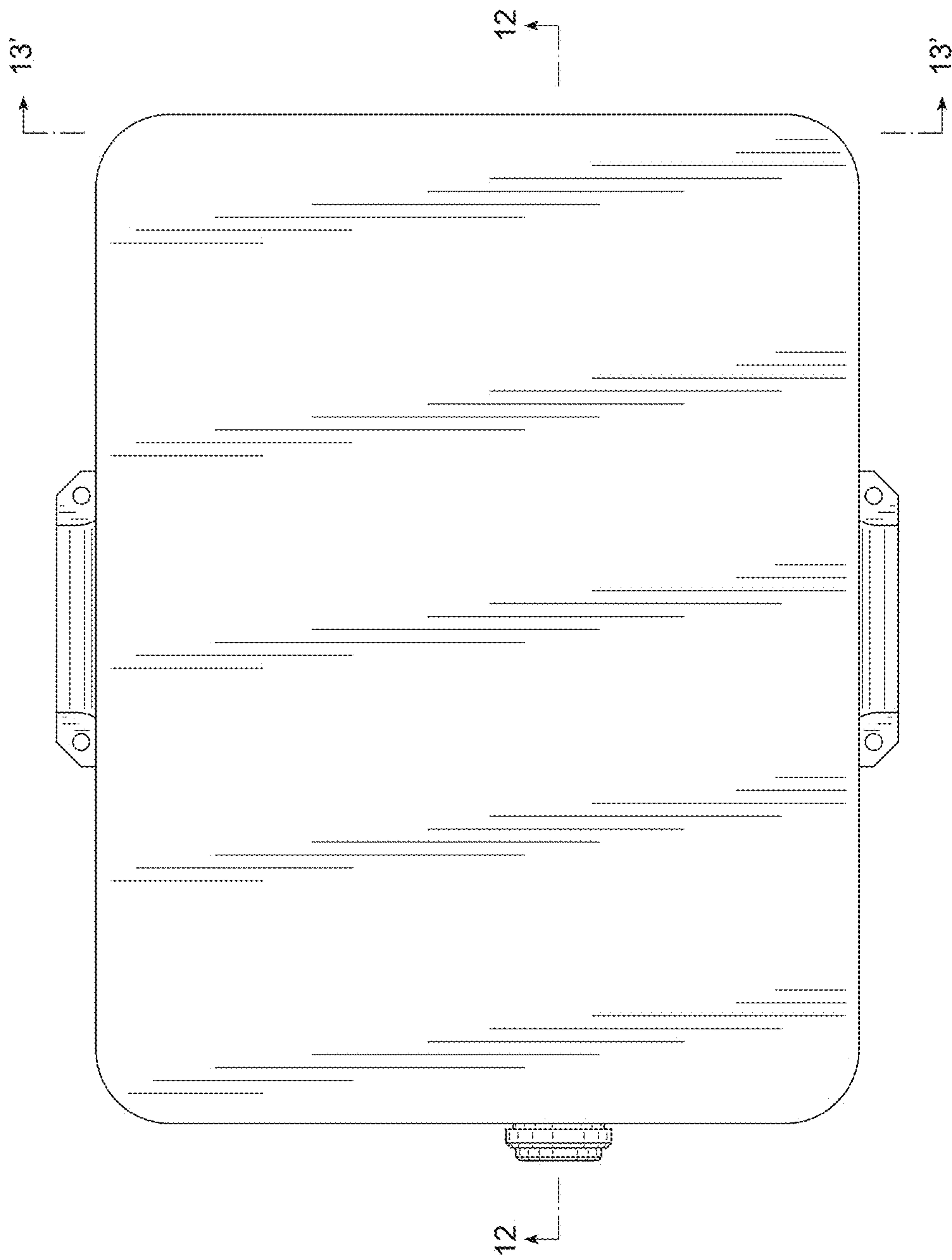


FIG. 3

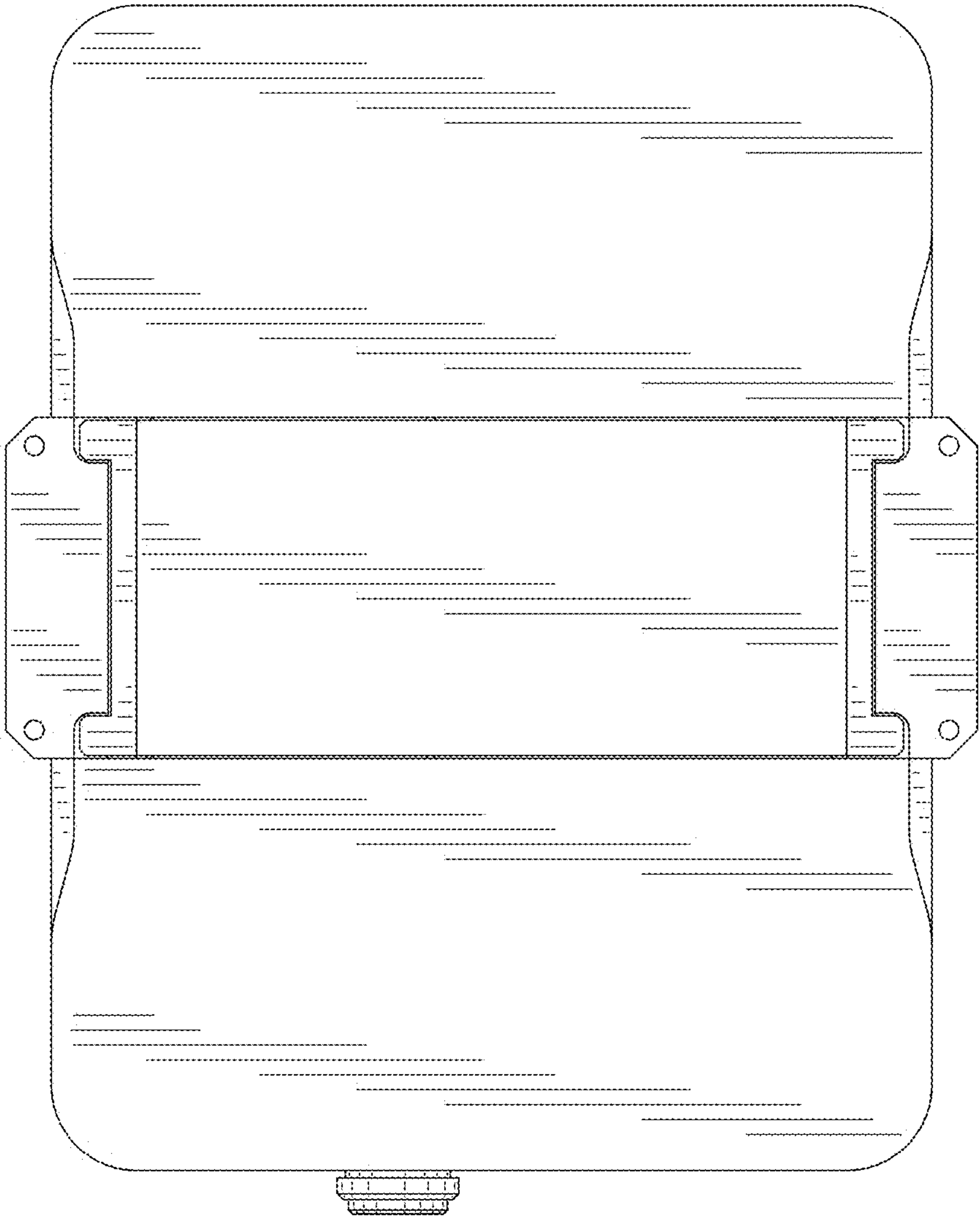


FIG. 4

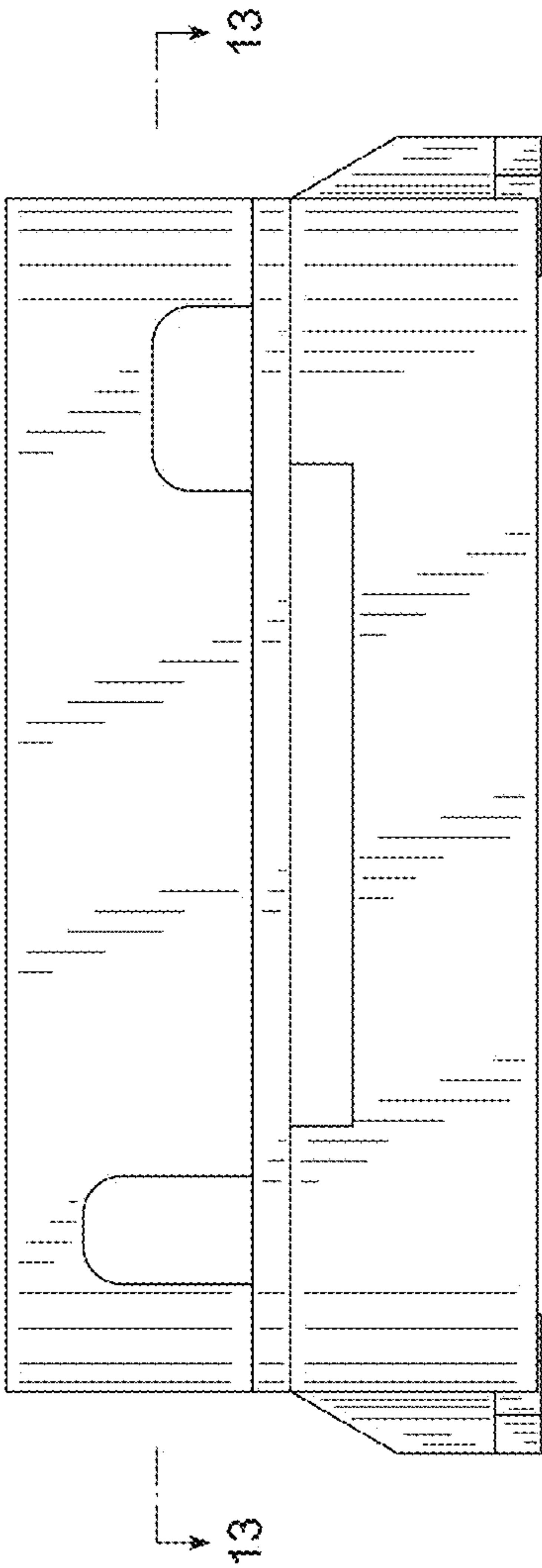


FIG. 5

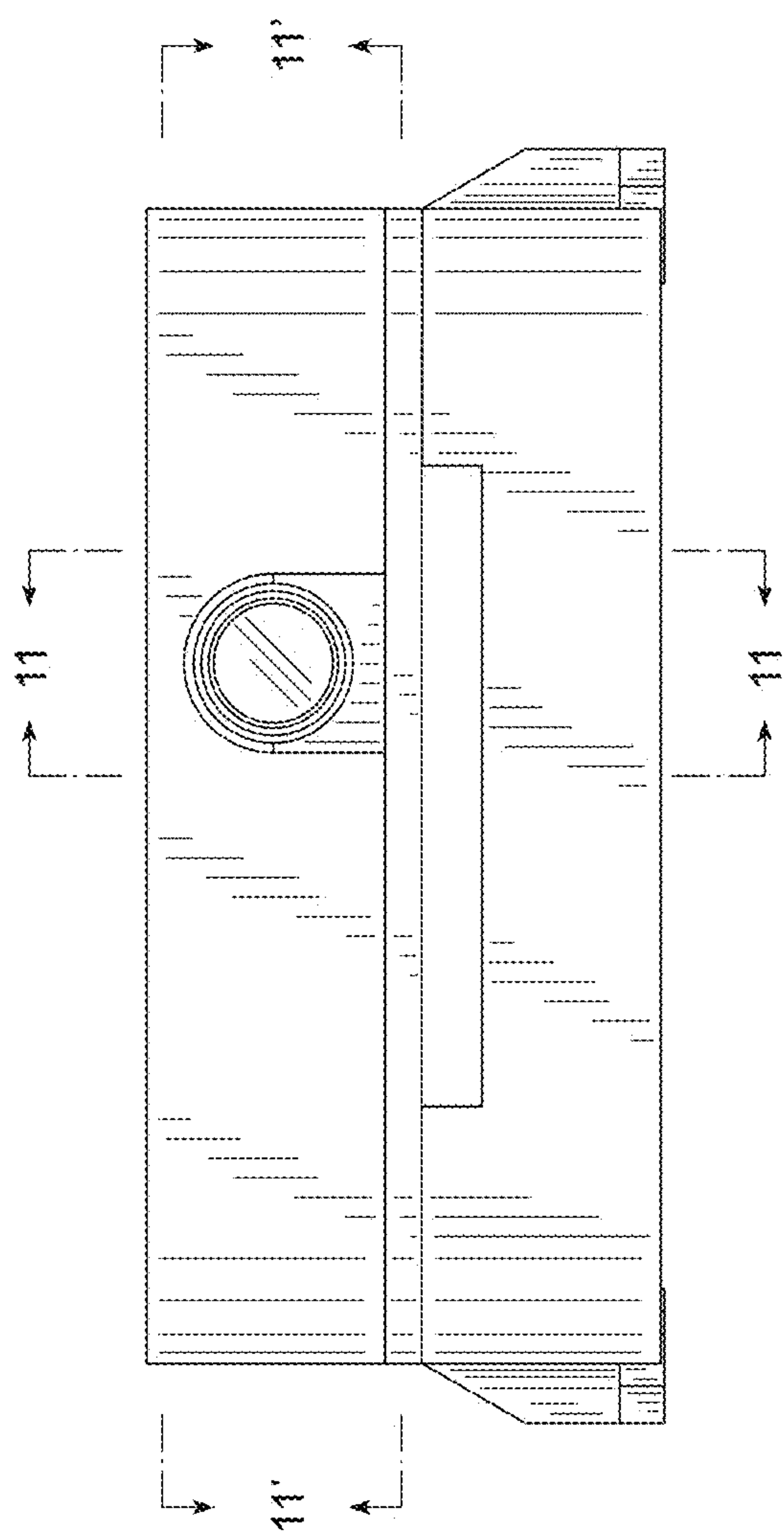


FIG. 6

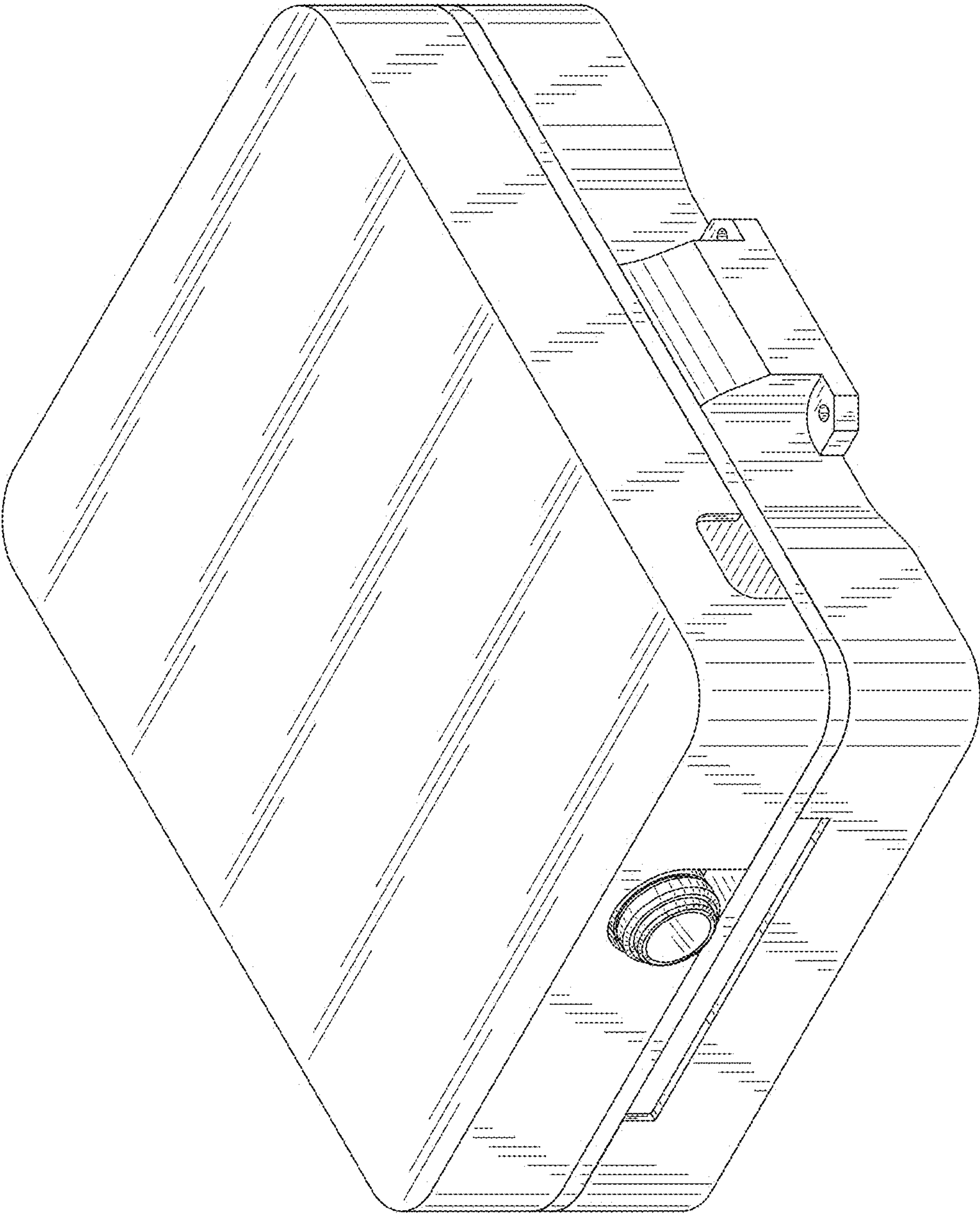


FIG. 7

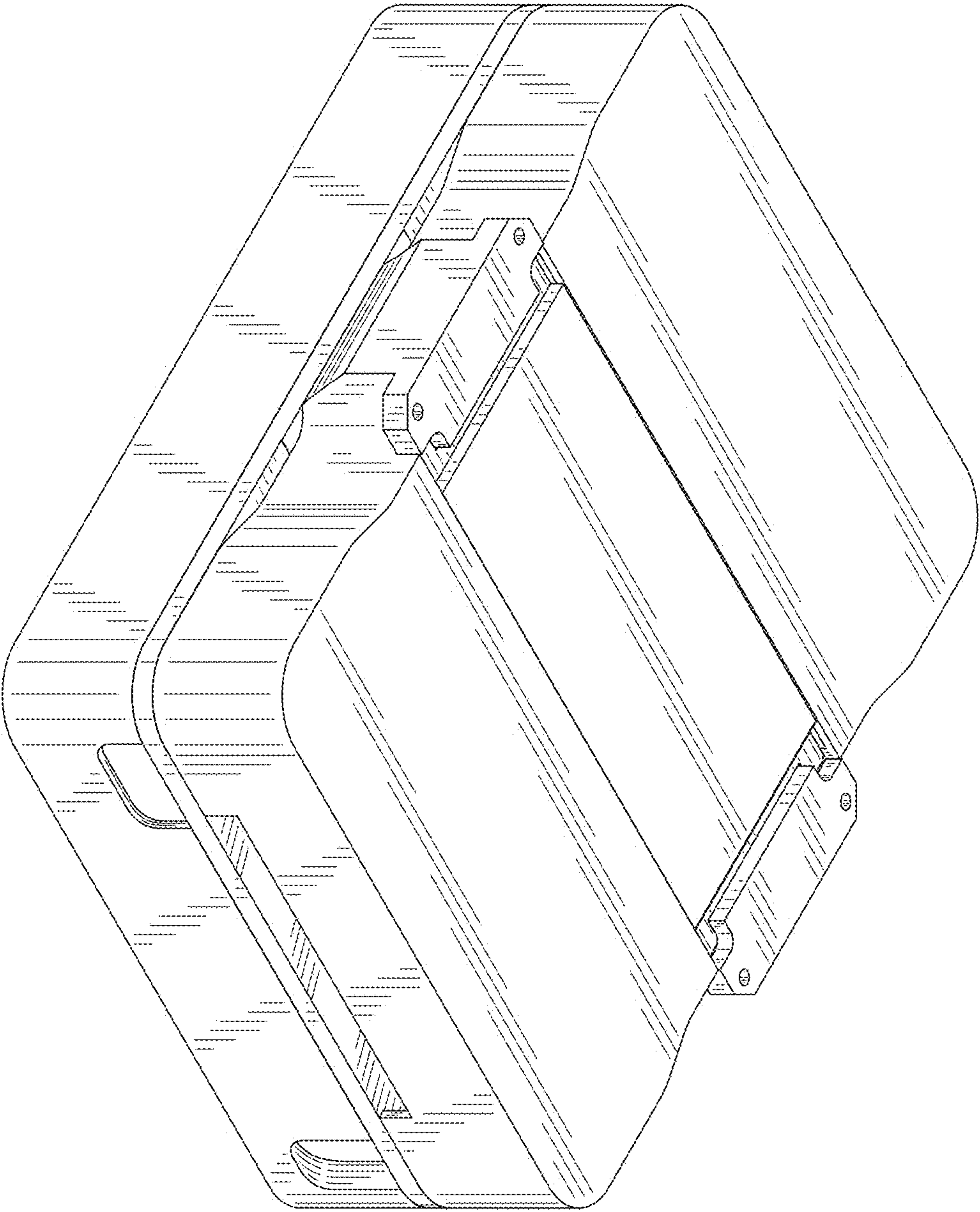


FIG. 8

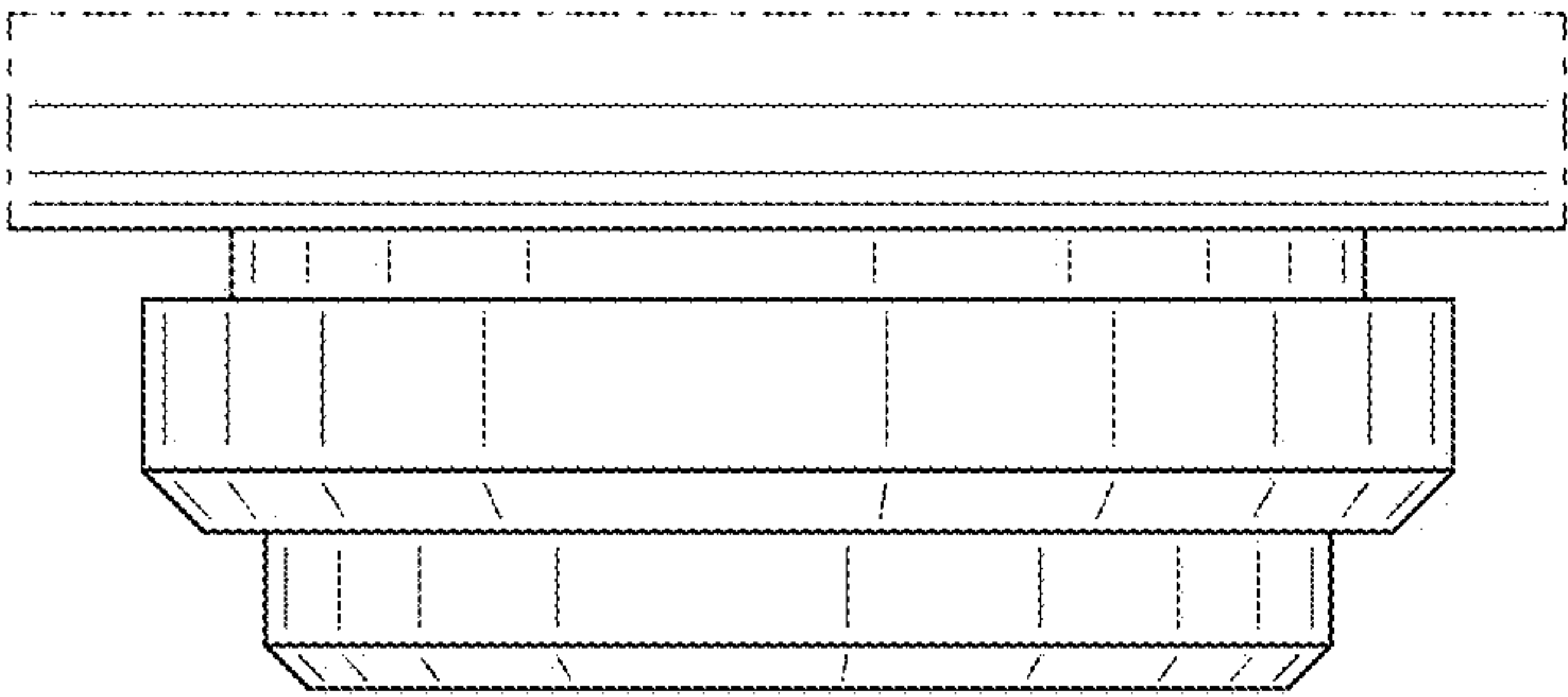


FIG. 9

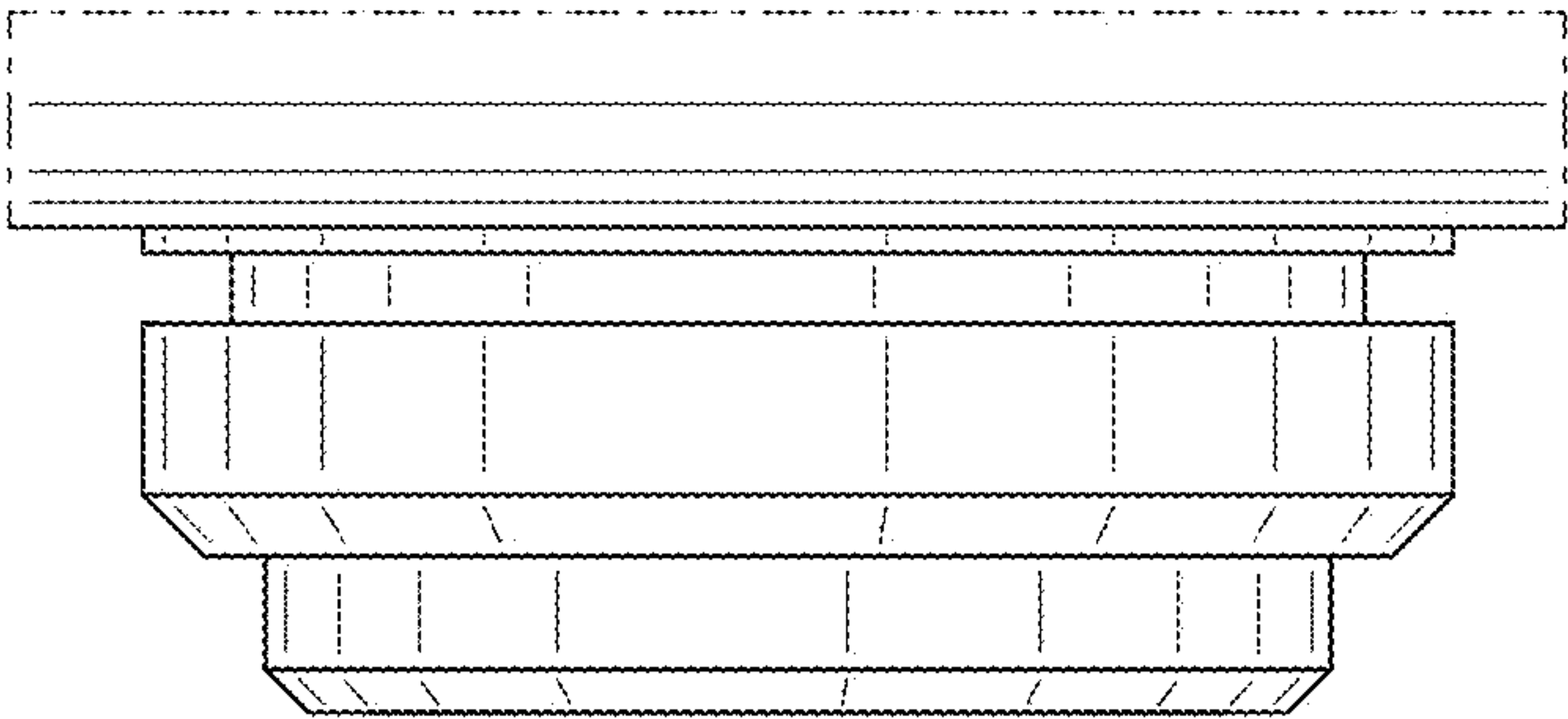


FIG. 10

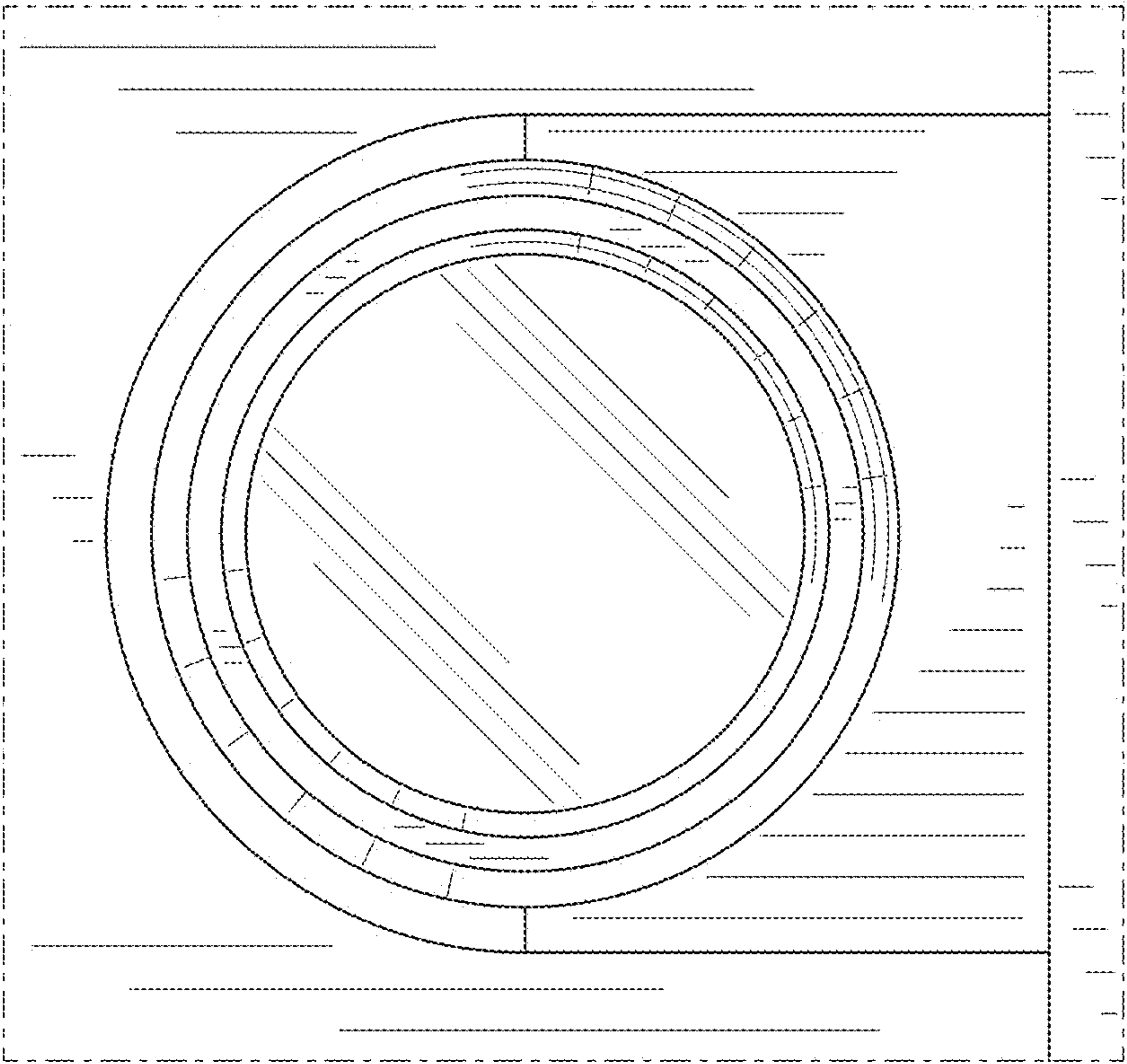


FIG. 11

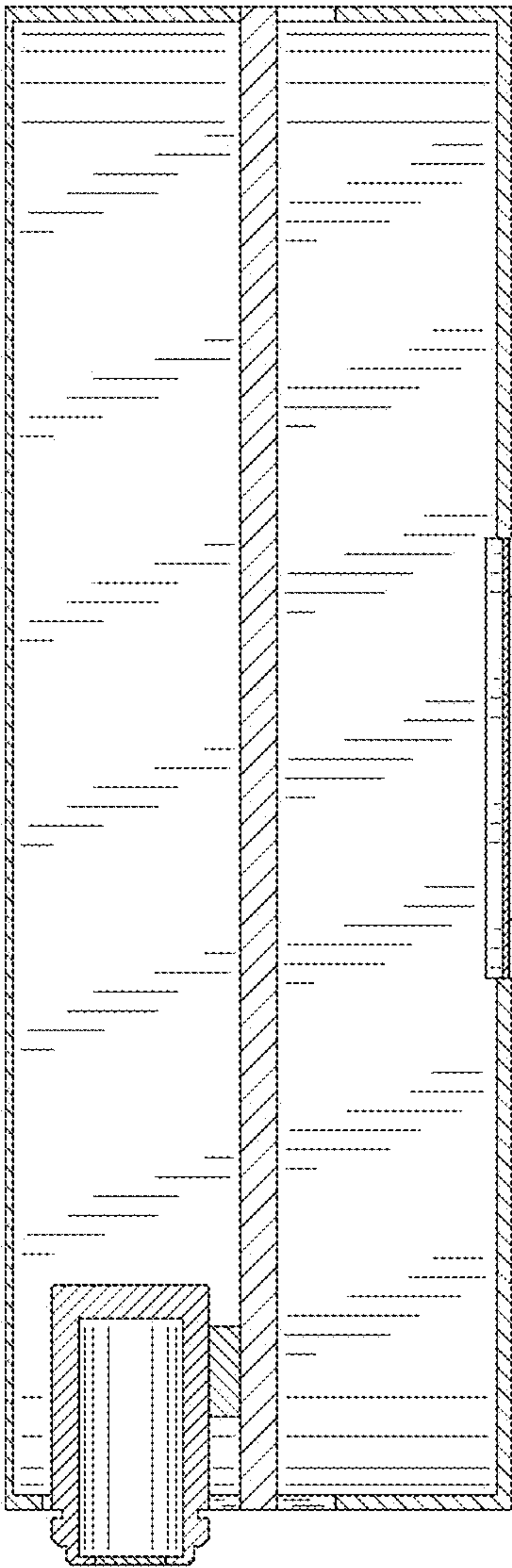


FIG. 12

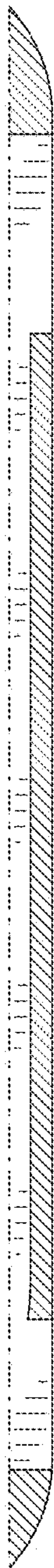


FIG. 13